
Development of a Very Dense Liquid Cooled Compute Platform

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Goals

■ Stated

- ❑ Achieve a data center infrastructure efficiency (DCiE) of better than 0.85 vs today's average of approx. 0.61
- ❑ Be capable of effectively supporting HPC applications yet have a manufacturing cost that makes it cost effective for mainstream applications.
- ❑ Have the capability of being cooled without the use of refrigeration systems for most of the year in the majority of US locations.

■ Extended

- ❑ 100KW power and cooling per rack
- ❑ Open platform enabled for Compute, Storage, Networking
- ❑ Upgraded power train, virtual I/O for additional energy saving

Team Members/Contributors

Team

Clustered Systems Company
extreme green electronics cooling

 **Liebert**[®]
Keeping Business in Business[™]

 **EMTEC**

SLAC
NATIONAL ACCELERATOR LABORATORY

Funding



Contributors



aqs

**ONE STOP
SYSTEMS**


EMERSON[™]
Network Power

 **SMART**[®]
Modular Technologies

**California
Machining
Center**

 **Bodycote**

TechShop
BUILD YOUR DREAMS HERE[™]

The Choice.....

Air

Refrigerant



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— 5500x volume →

← 90% Less Energy
1000% Higher Compute Density



👍 Small Pipes

👍 Few pumps

👎 **BIG** Ducts

👎 Many fans

The Choice (cont)....

Refrigerant

70C/158F

Low Rt



Wheee
e heat's
gone

30C/86F

Air



70C/158F

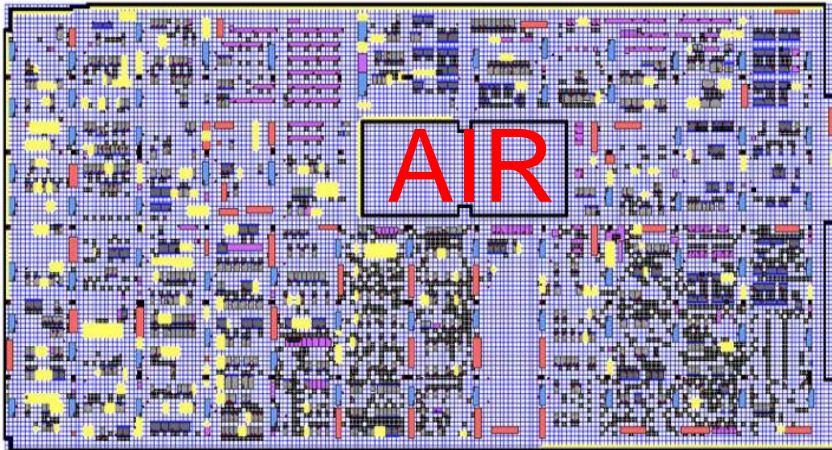
Gotta go in
the energy
hole to get rid
of the heat

High Rt

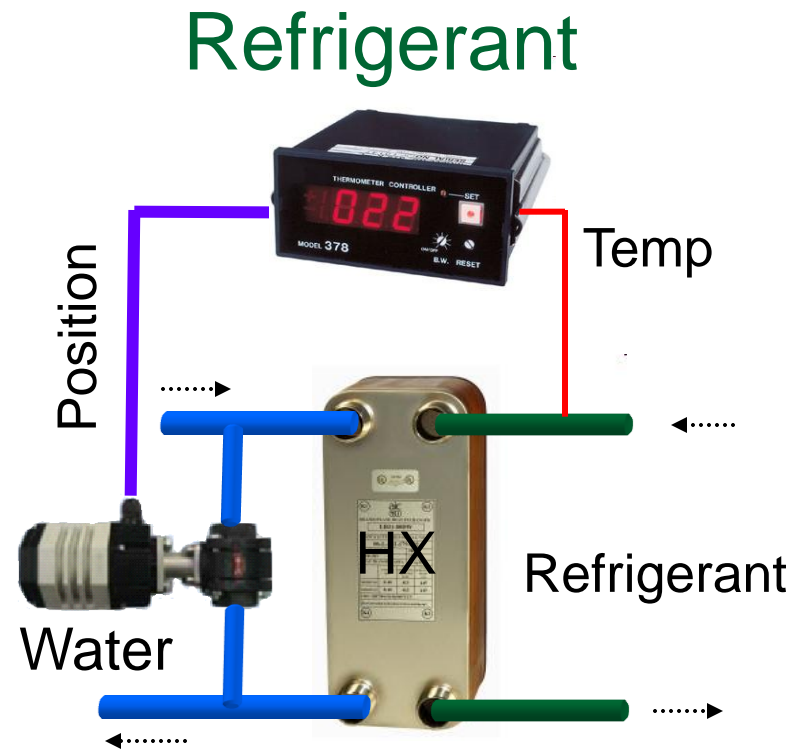
Add Energy

10C/50F

Control – Or Not

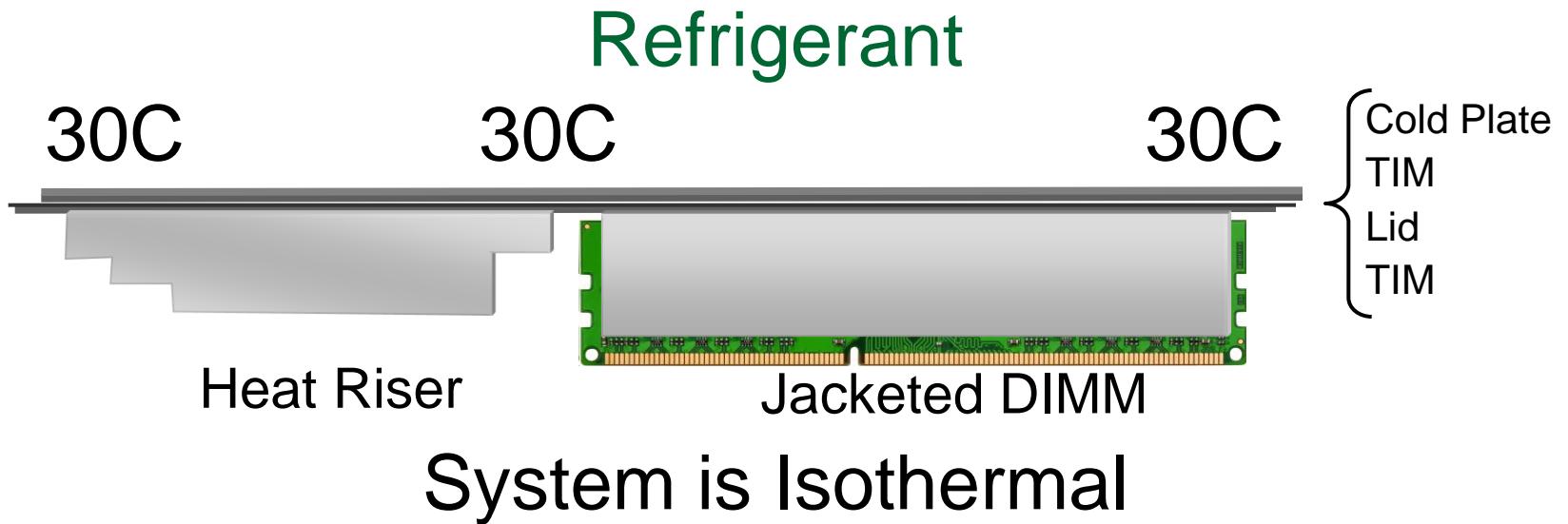
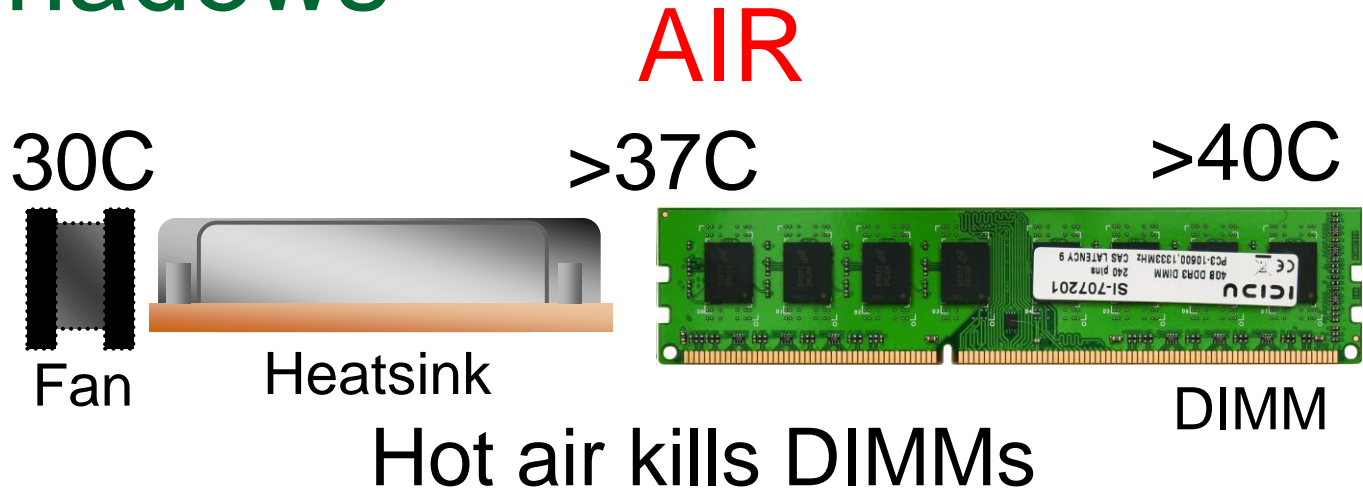


922 thermal sensors	87 in plenum
62 pressure sensors	72 discharge + 72 return
72 flow sensors	492 @ inlet (class #1)
42 humidity sensors	283 @ network

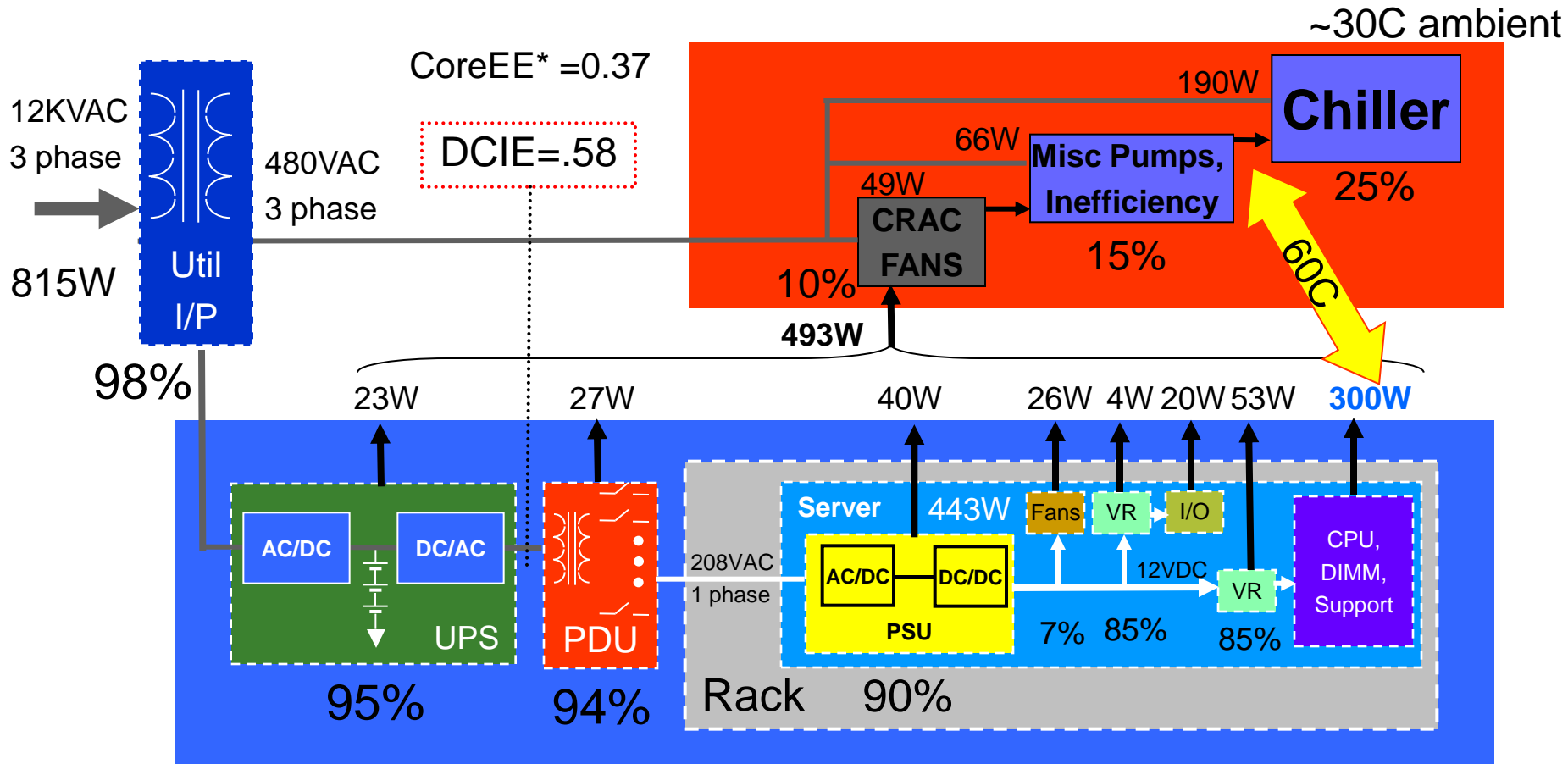


Simple proportional control is sufficient
Refrigerant section is isothermal

Shadows



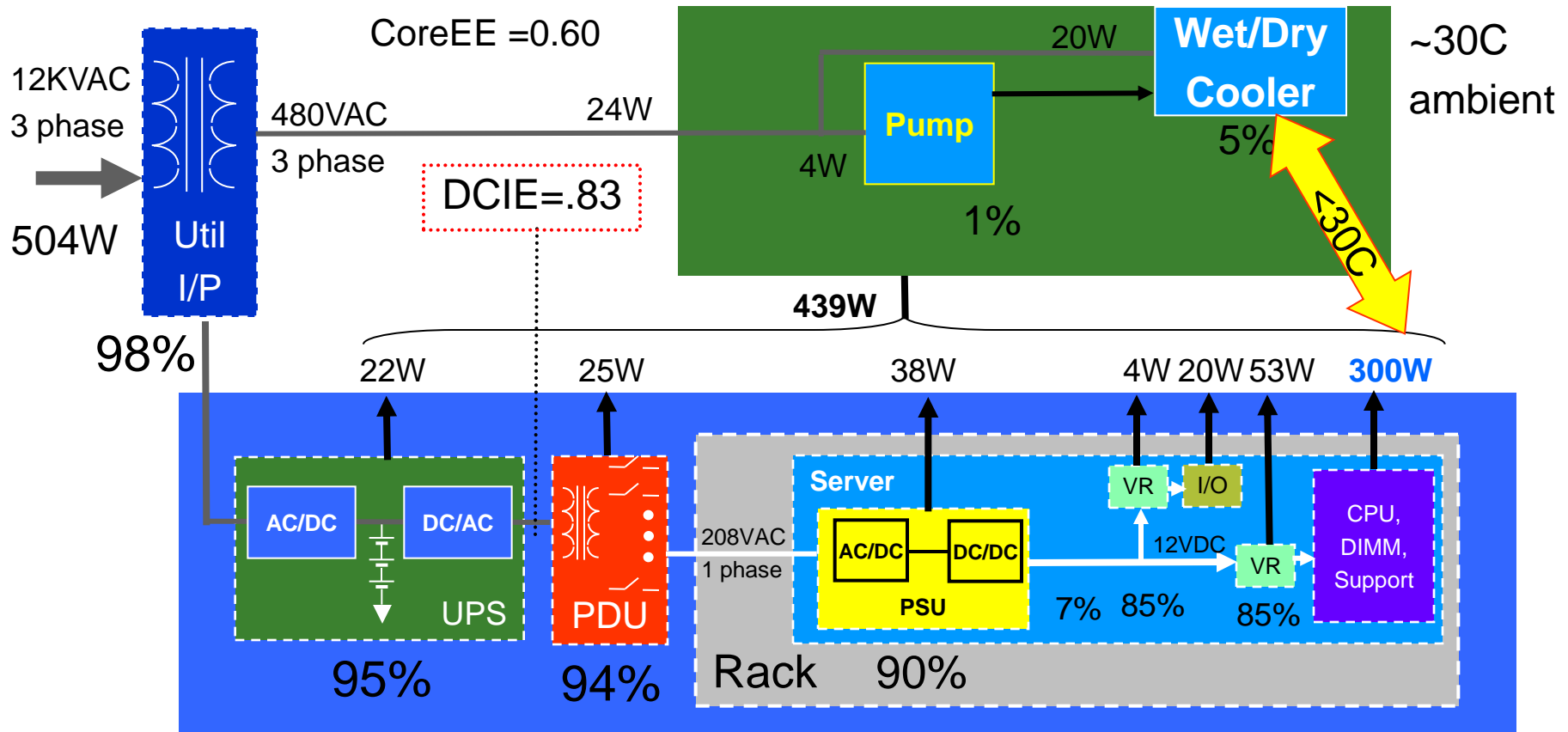
Where the Power Goes: Air



- Legacy air cooled system with water cooled chiller
- Air system's high thermal resistance forces chiller use

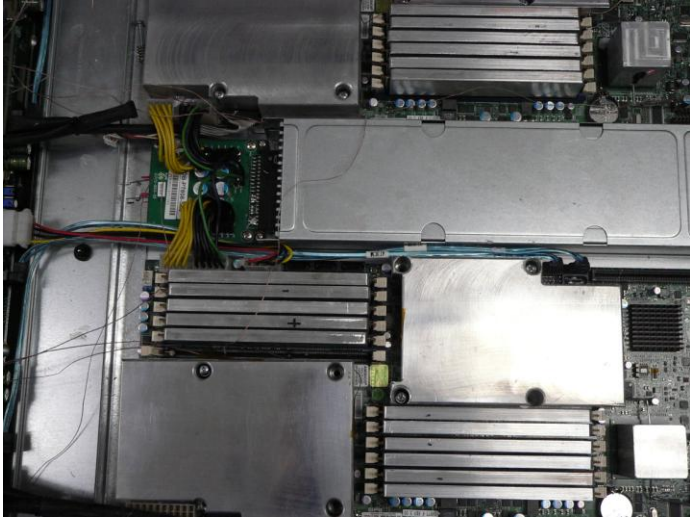
*CPU+DIMM pwr/total power

Where the Power Goes: Refrigerant



- All fans eliminated
- Lowered thermal resistance enables 95% economizer use or total chiller elimination

Direct Touch Refrigerant



Converted 4 CPU
Server Example:
Fans & Heatsinks
replaced by heat
risers



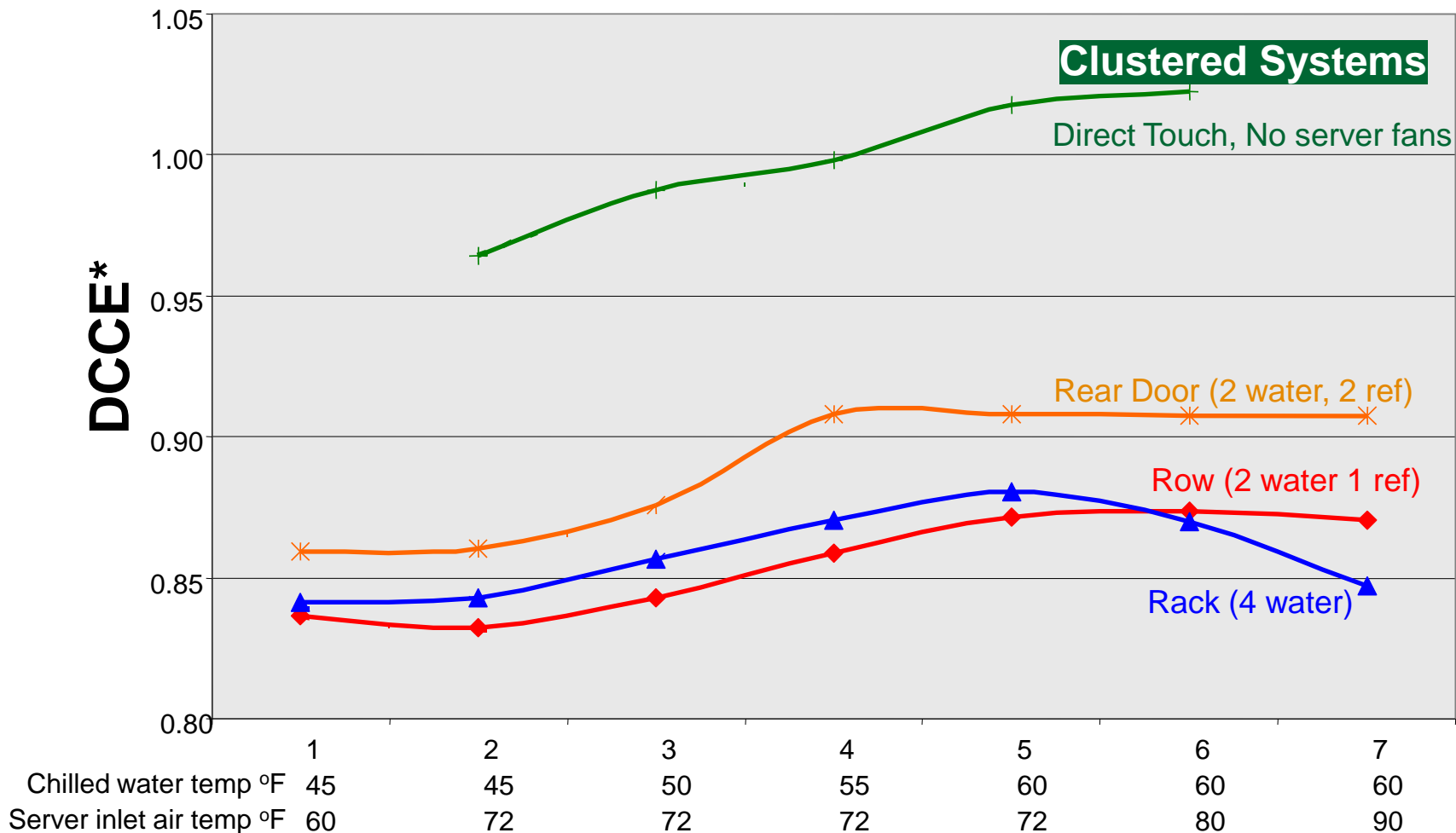
Rack mounted cold
plates (1/server)
remove heat
through specially
treated server lid



Liebert XDS
20KW & 40KW options

Chill Off II Results

Direct touch cooling demonstrated most efficient

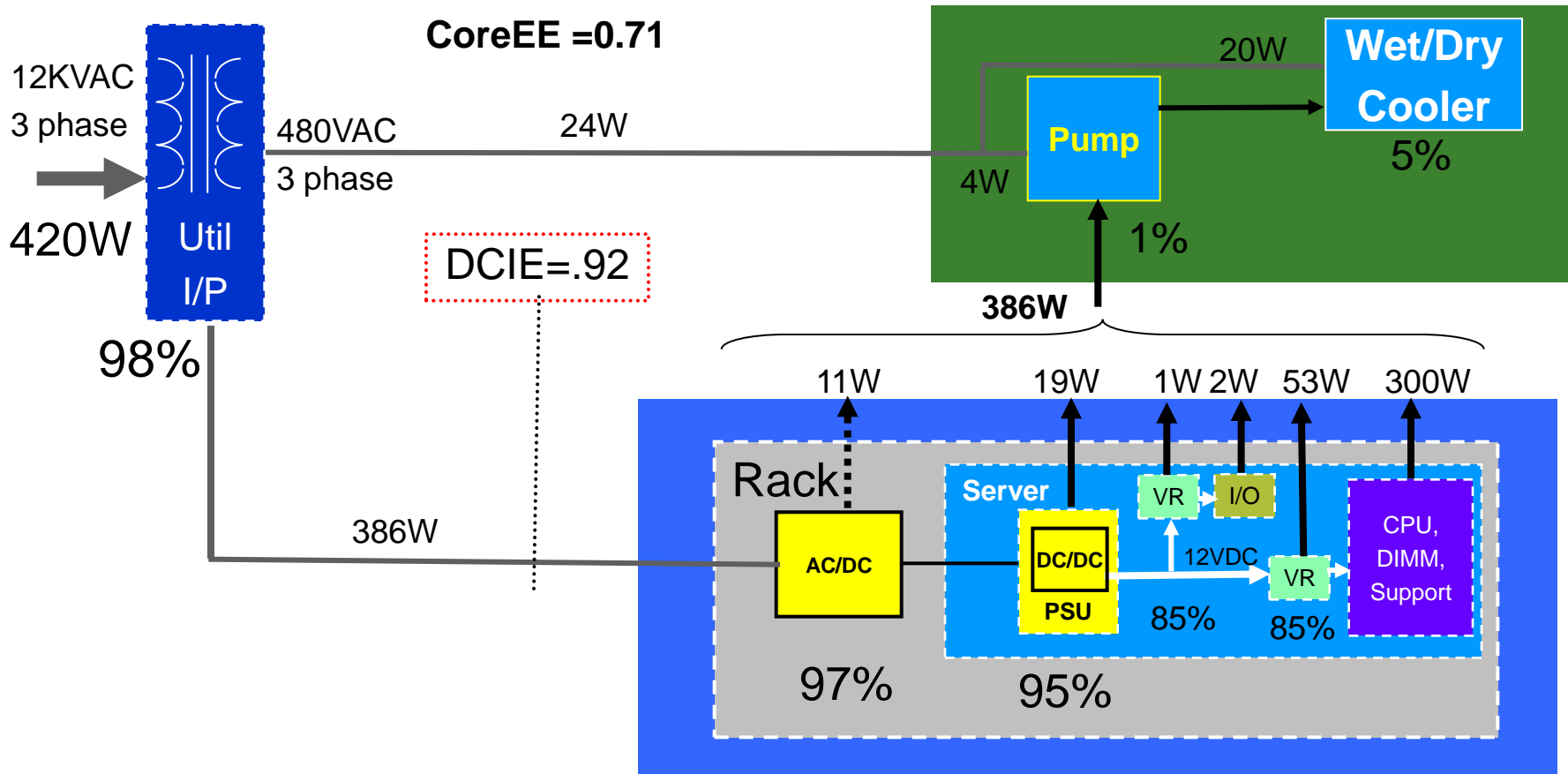


* Data Center Cooling Efficiency

Source: Lawrence Berkeley Labs

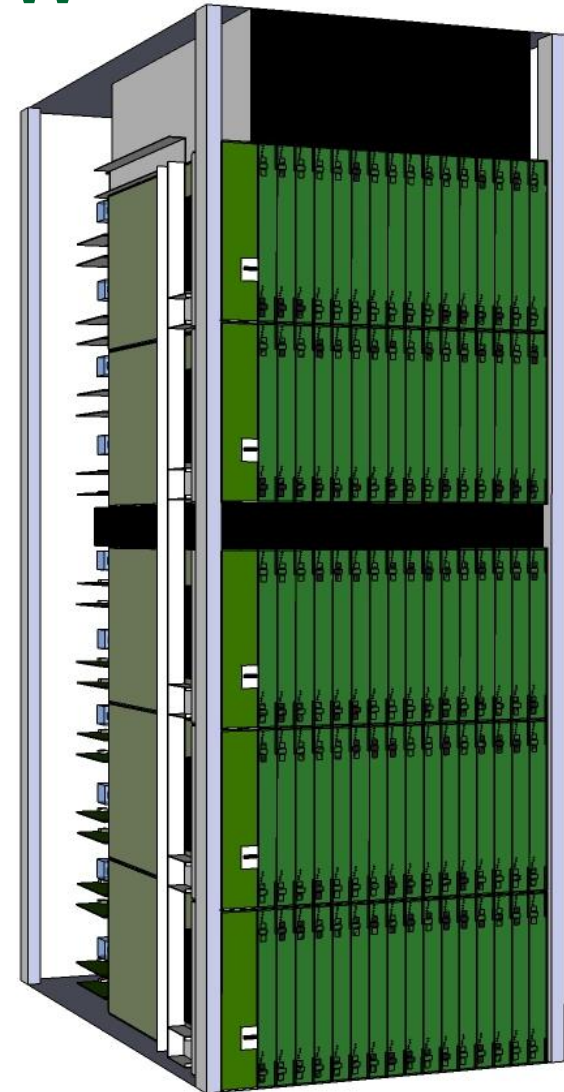
15%-20% Additional Energy Savings

I/O Virtualization, DC power

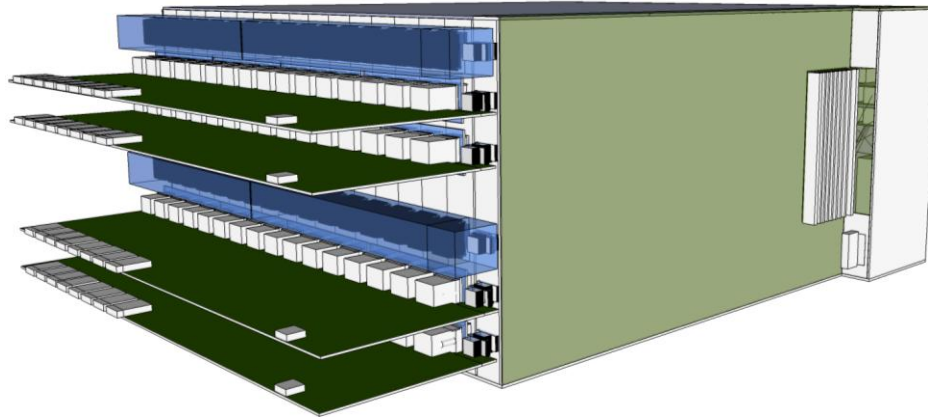


100KW Rack Overview

- 5 Chassis
 - 80 blades
- 100KW power & cooling
 - Proprietary non invasive liquid cooling system
 - 480VAC to 380VDC rectifier available
- Open System
- All electronics field replaceable



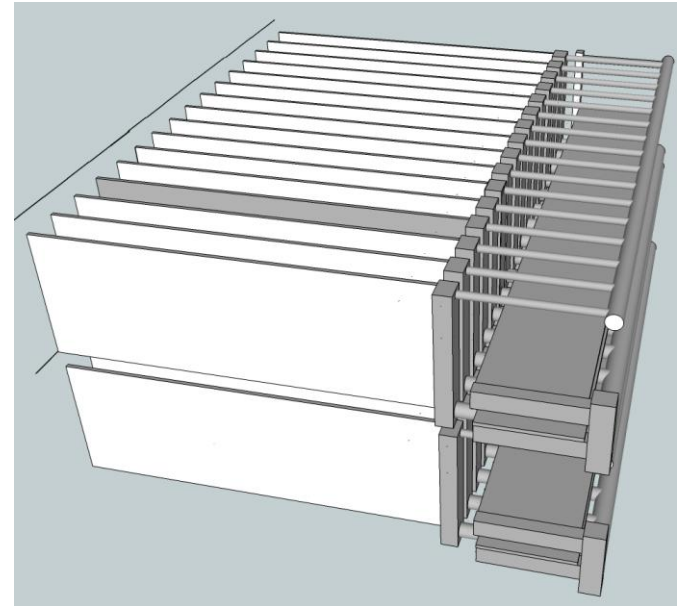
Architecture-Chassis



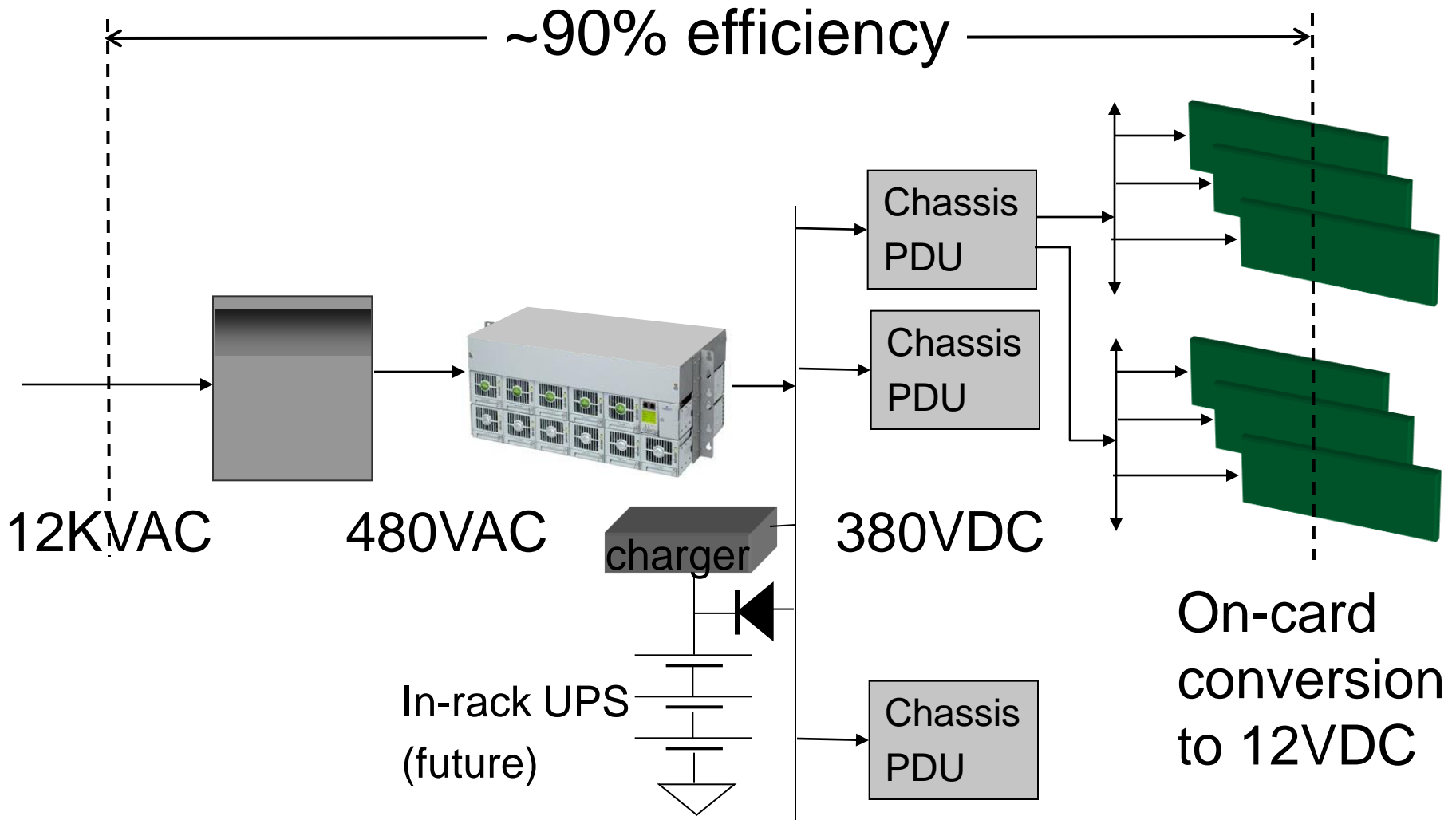
- 16 blade capacity
 - 1-2 circuit boards in each
 - 2 cold plates per blade
- 4 removable activeplanes for switching
- 20 KW power distribution unit

Cooling System

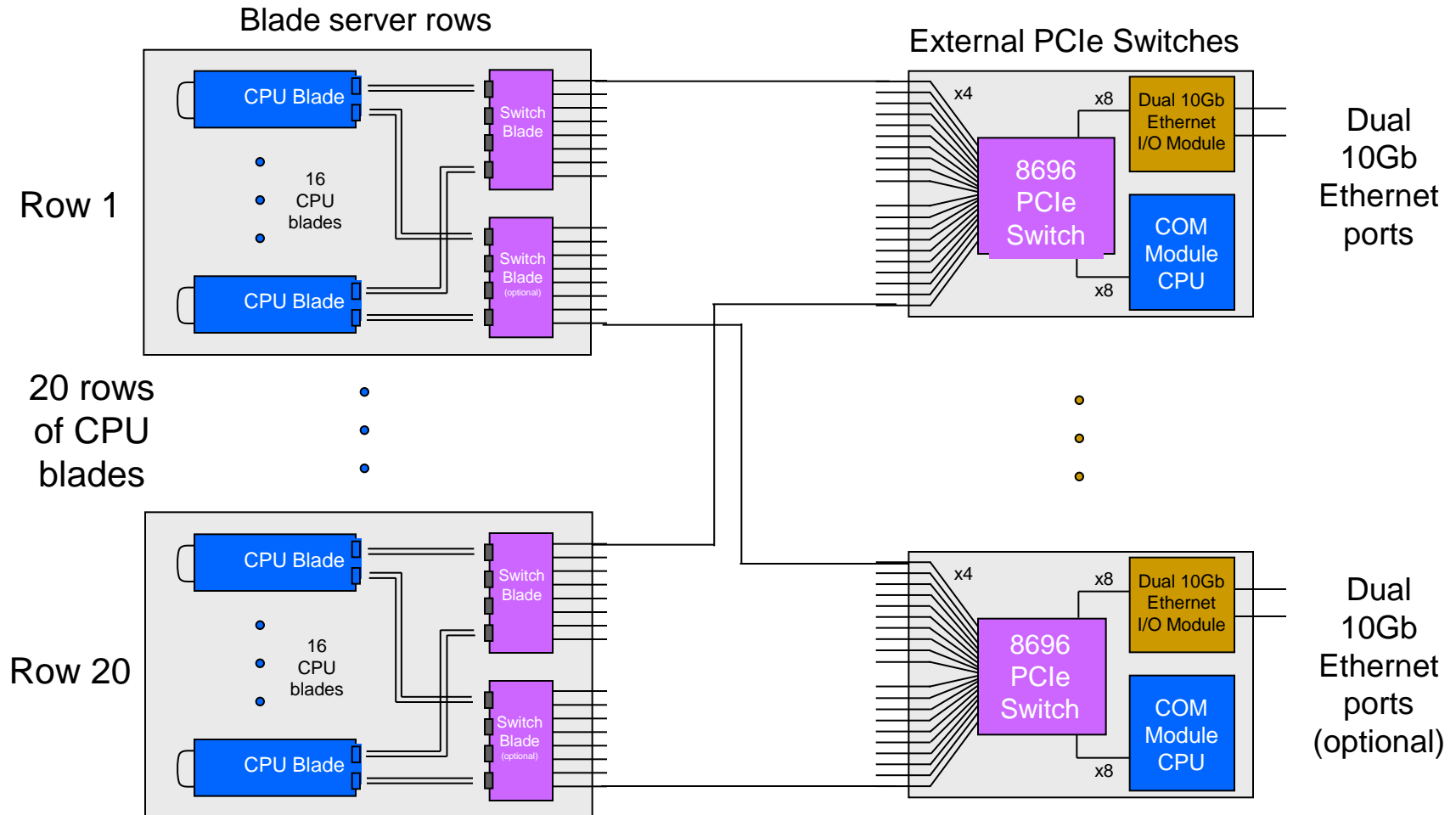
- 2 rows of 16 cold plates for motherboard cooling
 - >600W per plate capability
- 4 plates for activeplane cooling
 - 500W per plate



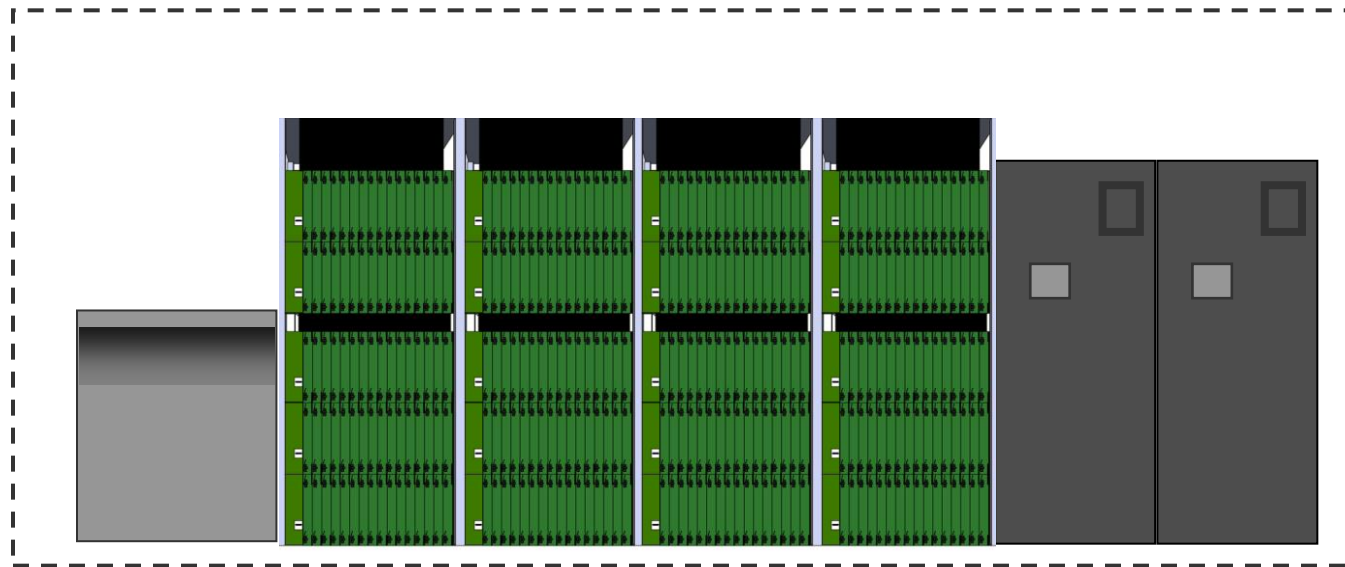
Power Train



System Intercommunication Architecture: I/O virtualization



Application Example – 20' Container



12KV-480VAC
400KVA Xfmr

CSys Racks

2 x Liebert XDP



Adiabatic cooler+
chiller (optional*)

- Capacity: 640 Servers
- 400KW power and cooling
- Infrastructure cost ~\$1,000 per server

*Very hot climates

Potential Cost Savings

3.2MW Data Center

	Next-gen	HP Ultra-modular	Clustered	% reduction
Site and facility development	\$58,000,000	\$26,000,000	\$ 9,207,360*	84%/65%
Total annual energy cost	\$3,053,106	\$2,637,677	\$ 2,136,518 **	30%/19%
Total annual water cost	\$67,440	\$7,418	\$ 6,454	90%/13%

*Estimated price for 8 container based 400KW modules

** Based upon new blade server design

Status

- PCB layouts complete, prototypes mid/end April
- Mechanical design 90% complete, assemblies deliveries start mid April
- Cold plate prototypes tested OK
- Chassis test facility designed and built
- Chassis test starts early June
- First rack completes in August

Summary

- Mechanical/cooling framework for multiple applications
- Open system
 - Mix and match switches and blades
 - PCIe, IB, Ethernet, etc.
 - CPU, GPU, Storage, Router
- All electronics field replaceable
 - Forward legacy capability
- ~\$20M/PetaFLOPS all included
 - Facilities, hardware etc.
- No special facilities required
 - Direct touch cooling

Hot Water Cooling

Low device to sink (outside air) thermal resistance

